

Data Sheet Of Thermal Conductive Gel TSP-D10X0 Series

Characteristic:

- Thermal conductivity=1.0--6.0W/mk or customized.
- High thermal conductivity, low thermal resistance.
- Small Young modulus, ultra-low stress.
- Easy to use for dispensing operations.
- Good electrical insulation performance and temperature resistance.



Product's Description

The Common Series Of Single-component Thermal Gel is a single-component, highly adaptable thermal interface material, this material has better stress and strain values than ultra-soft thermal pad it can be automatically dispensed and coated, and is the best choice in cases the multiple chips share one heat sink/structure.

Custom Service

1. Can choose dispensing or coating.
2. Can be filled according to customize requirements.

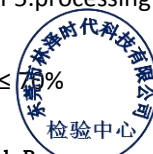
Product Models	TSPD-1020	TSPD-1030	TSPD-1040	TSPD-1050	TSPD-1060	TSPD-1070	Unit	Test Standard
Color	Pink	Pink	Blue	Blue	Blue	Blue	---	Visual
Density	3.4 (±0.2)	3.35 (±0.2)	2.95 (±0.2)	3.1 (±0.2)	3.2 (±0.2)	2.8 (±0.2)	g/cc	ASTM D792
Extrusion Rate	≥20	≥30	≥30	≥15	≥15	≥15	g/min	---
Minimum Filling Gap	≤0.2	≤0.2	≤0.2	≤0.03	≤0.03	≤0.03	mm	---
Volatilize Matter	≤200	≤200	≤200	≤200	≤200	≤200	PPM	GB269
Instantaneous Stress	≤10	≤10	≤10	≤10	≤10	≤10	Psi	GB/T7757
Static Compression stress	< 1	< 1	< 1	< 1	< 1	< 1	Psi	GB/T7757
UL Flammability Rating	V-0	V-0	V-0	V-0	V-0	V-0	---	UL-94
Continuous Use Temperature	-40±200	-40±200	-40±200	-40±200	-40±200	-40±200	°C	EN334
Thermal Properties								
Thermal conductivity	6	5	4	3	2	1	W/m-k	ASTM D5470
Thermal Resistance	≤0.06 @20psi	≤0.06 @20psi	≤0.06 @20psi	≤0.08 @20psi	≤0.12 @20psi	≤0.7 @20psi	°Cin ² /W	ASTM D5470
Electrical Properties								
Breakdown Voltage	≥5	≥5	≥5	≥2.5	≥8	≥8	kv/mm	ASTM D149
Volume Resistivity	≥10 ⁸	≥10 ⁸	≥10 ⁸	≥10 ¹⁰	≥10 ¹⁰	≥10 ¹⁰	Ω.cm	ASTM D257

Typical Applications

1. Semiconductor blocks and heat sinks
2. Used for LED lighting fixtures and luminous bodies
3. Automotive and consumer sectors
4. Glue or directly coat into various thicknesses and shapes for high-performance central processing and graphics card processors

Refrigerated or stored in a dark place, storage temperature: ≤ 25 °C, storage humidity: ≤ 75%

Packaging specifications: 30cc/55cc/300cc/2600cc



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